

TRANSFER MACHINE, SUBSTRATE PROCESSING APPARATUS, METHOD OF
PROCESSING SUBSTRATE, METHOD OF MANUFACTURING SEMICONDUCTOR
DEVICE, AND PROGRAM

ABSTRACT

There is provided a technique that includes: (a) at least one end effector configured to be capable of being inserted into a holder configured to accommodate a plurality of substrates in multiple stages without being in contact with the plurality of substrates, and gripping a corresponding substrate of the plurality of substrates respectively; and (b) at least one substrate detector arranged at a predetermined relative position with respect to the at least one end effector and configured to be capable of optically detecting the corresponding substrate in at least one selected from the group of a state in which the at least one end effector is inserted into the holder and a state in which the at least one end effector grips the corresponding substrate.

Fig. 3